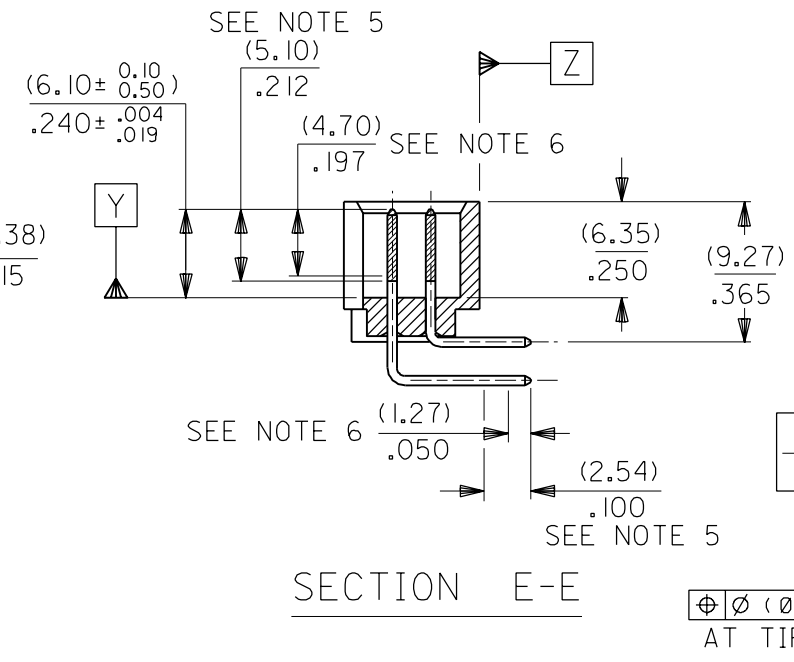
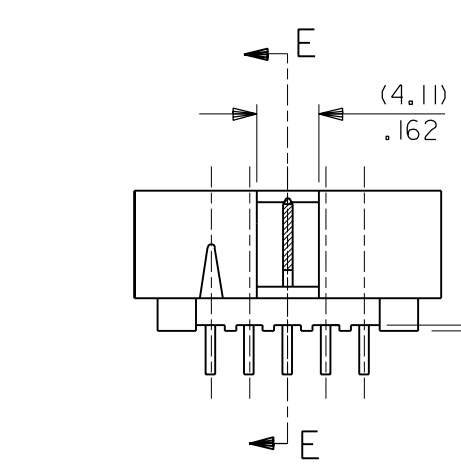
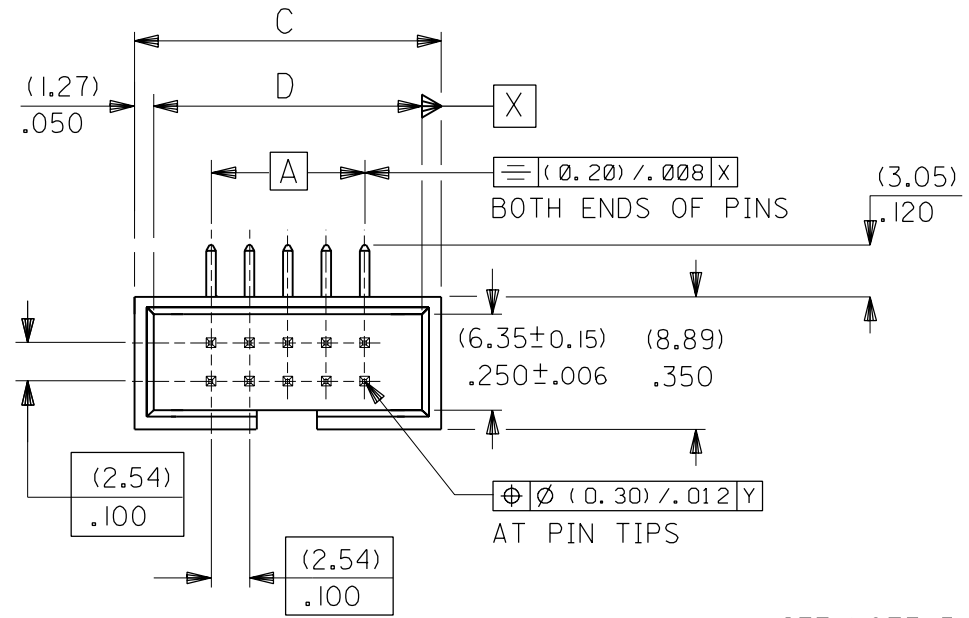
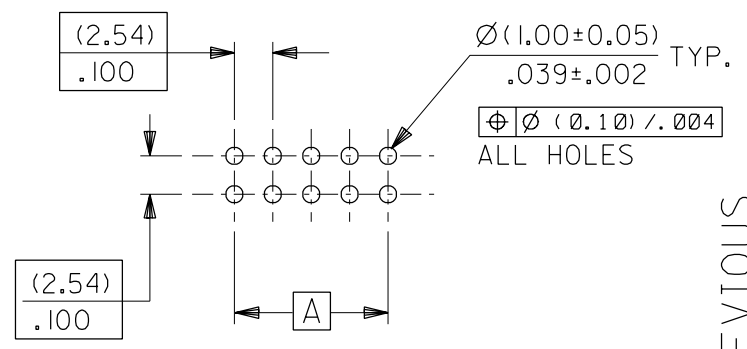
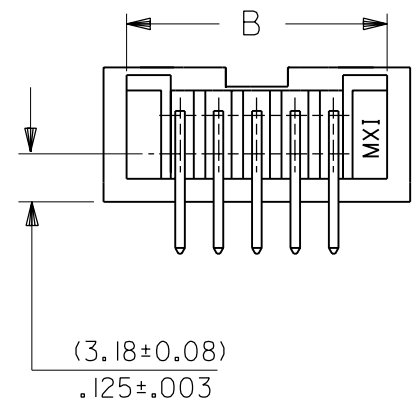


PART NO. SEE CHART  
 DWG. NO. SDA-90709



RECOMMENDED P.C. BOARD HOLE LAYOUT



FOR PREVIOUS DRAWING ISSUES SEE MRI.

LEAD FREE CONVERSION  
 EC No. E2004-0792  
 DRWN: PSHEAHAN 04/02/17  
 CHK'G: / / / /  
 APPR: / / / /  
 H LTR

THIRD ANGLE PROJECTION		DRWG BY <b>POB</b>
DIMENSIONS SHOWN ( METRIC ) INCH UNLESS OTHERWISE SPECIFIED TOLERANCES: ANGULAR ±2° INCH ( METRIC )		CHK'D BY
3 PLACE ± .010		APP'D BY
2 PLACE ± .	± 0.25	SCALE <b>2 : 1</b>
1 PLACE ±		
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		
DESIGN DIMENSION (PRIMARY)	<input checked="" type="checkbox"/> (MM) <input type="checkbox"/> IN.	
EQUIVALENT DIMENSION (SECONDARY)	<input type="checkbox"/> (MM) <input checked="" type="checkbox"/> IN.	

PART NUMBER	CIRCUIT SIZE	DIM A	DIM B	DIM C	DIM D
90709-100*	10	(10.16) 0.400	(17.27) 0.680	(20.32) 0.800	(17.78) 0.700
90709-140*	14	(15.24) 0.600	(22.35) 0.880	(25.40) 1.000	(22.86) 0.900
90709-160*	16	(17.78) 0.700	(24.89) 0.980	(27.94) 1.100	(25.40) 1.000
90709-200*	20	(22.86) 0.900	(29.97) 1.180	(33.02) 1.300	(30.48) 1.200
90709-260*	26	(30.48) 1.200	(37.59) 1.480	(40.64) 1.600	(38.10) 1.500
90709-300*	30	(35.56) 1.400	(42.67) 1.680	(45.72) 1.800	(43.18) 1.700
90709-340*	34	(40.64) 1.600	(47.75) 1.880	(50.80) 2.000	(48.26) 1.900
90709-400*	40	(48.26) 1.900	(55.37) 2.180	(58.42) 2.300	(55.88) 2.200
90709-500*	50	(60.96) 2.400	(68.07) 2.680	(71.12) 2.800	(68.58) 2.700
90709-600*	60	(73.66) 2.900	(80.77) 3.180	(83.82) 3.300	(81.28) 3.200
90709-640*	64	(78.74) 3.100	(85.85) 3.380	(88.90) 3.500	(86.36) 3.400

- NOTES:**
- MATERIALS: WAFER; 15% GLASS FILLED PBT, 94V-0, PINS; (0.635)/.025 SQ BRASS WIRE.
  - PIN SOLDERABILITY PER MOLEX SPEC. ES-152
  - PIN PUSHOUT FORCE (.9072KG)/2LBS MIN.
  - WAFER TO BE FLAT WITHIN (0.03MM/CM)/.003IN/IN
  - THESE DIMENSIONS DEFINE THE MINIMUM COVERAGE FOR PLATING.
  - THESE DIMENSIONS DEFINE THE MEASURING POINT FOR PLATING THICKNESS.
  - FINISH (PER ES-88):
    - 90709-\*\*\*1: GOLD PLATE (0.38um)/15uin MIN. IN SELECTED AREA. (TYPE 587)  
TIN PLATE (1.9um)/75uin MIN. IN SELECTED AREA. OVER (1.3um)/50uin MIN. NICKEL OVERALL.
    - 90709-\*\*\*2: GOLD PLATE (0.76um)/30uin MIN. IN SELECTED AREA. (TYPE 599)  
TIN PLATE (1.9um)/75uin MIN. IN SELECTED AREA. OVER (1.3um)/50uin MIN. NICKEL OVERALL.
    - 90709-\*\*\*3: GOLD PLATE (0.10um)/5uin MIN. IN SELECTED AREA. (TYPE 608)  
TIN PLATE (1.9um)/75uin MIN. IN SELECTED AREA. OVER (1.3um)/50uin MIN. NICKEL OVERALL.

PRE-RELEASE REFERENCE USE ONLY

REVISE ONLY ON CAD SYSTEM		SH.	REV.
CAD/CAM FILENAME SA90709X1 DGN	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INC. & SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		
TITLE <b>(2.54)/.100 R/A DUAL ROW LOW PROFILE SHROUDED HEADER ASSEMBLY</b>			
molex MOLEX EUROPE		SHEET NO. 10F1	DATE 9/10/01
PART NO. SEE CHART	DWG. NO. SDA-90709	SIZE B	